

High Current, High Frequency, Power Inductors

FLAT-PAC™ FP0807 Series



Description:

- Halogen free
- 125°C maximum total temperature operation
- 7.4 x 7.6 x 7.0mm surface mount package
- · Ferrite core material
- · High current carrying capacity, Low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 70nH to 220nH
- · Current range from 35 to 108 amps
- Frequency range up to 2MHz
- · RoHS compliant

Applications:

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Desktop and server VRMs and EVRDs
- · Notebook regulators
- Data networking and storage systems
- Graphics cards and battery power systems
- · Point-of-load modules
- DCR sensing

Environmental Data:

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (Range is application specific)
- Solder reflow temperature: J-STD-020D compliant

Packaging:

• Supplied in tape and reel packaging, 600 parts per reel, 13" diameter reel

Product Specifications							
Part Number ⁷	OCL1 ± 10% (nH)	FLL ² Min. (nH)	I _{rms} ³ (Amps)	I _{sat} 1 ⁴ @ 25°C (Amps)	I _{sat} 2 ⁵ @ 125°C (Amps)	DCR (mΩ) @ 20°C	K-factor ⁶
FP0807R1-R07-R	70	50		108	79		520
FP0807R1-R10-R	100	72		77	55		520
FP0807R1-R12-R	120	86		66	48		520
FP0807R1-R16-R	160	115	49	48	36	$0.50 \pm 6\%$	520
FP0807R1-R18-R	180	129		42	32		520
FP0807R1-R20-R	200	144		38	28		520
FP0807R1-R22-R	220	158		35	25		520

- 1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V_{rms}, 0.0Adc
- $^{\circ}$ Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V $_{rms}$, $I_{sat}1$
- 3 I_{rms} : DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.
- 4 Isat1: Peak current for approximately 20% rolloff at +25°C.
- 5 I_{sat}2: Peak current for approximately 20% rolloff at +125°C.
- 6 K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K * L * \Delta I * 10^{-3}$, B_{p-p} : (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).

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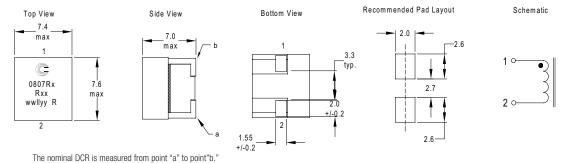
- 7 Part Number Definition: FP0807Rx-Rxx-R
 - FP0807 = Product code and size
- · Rx is the DCR indicator
- Rxx= Inductance value in μ H, R = decimal point "-R" suffix = RoHS compliant

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Dimensions - mm



The horninal Don is measured from point a -to point b

Part Marking: Coiltronics Logo

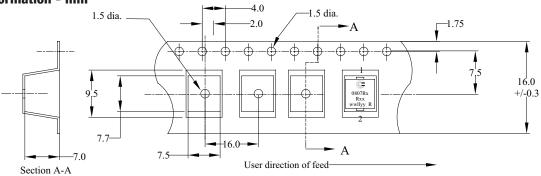
0807Rx (Rx = DCR Indicator)

 $Rxx = Inductance value in \mu H. (R = Decimal point)$

 $\mathsf{wwllyy} = \mathsf{Date}\;\mathsf{code}$

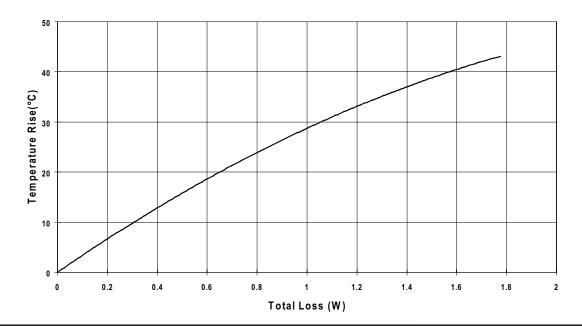
R = Revision level

Packaging Information - mm



Supplied in tape-and-reel packaging, 600 parts per reel, 13" diameter reel.

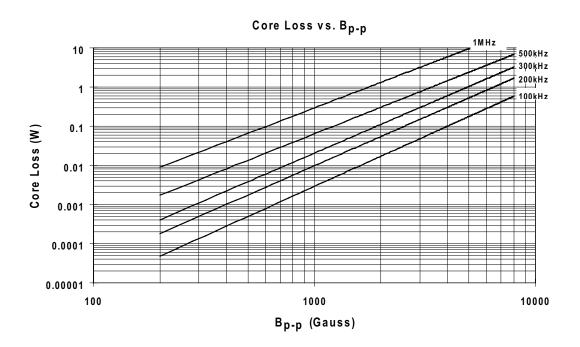
Temperature Rise vs. Total Loss



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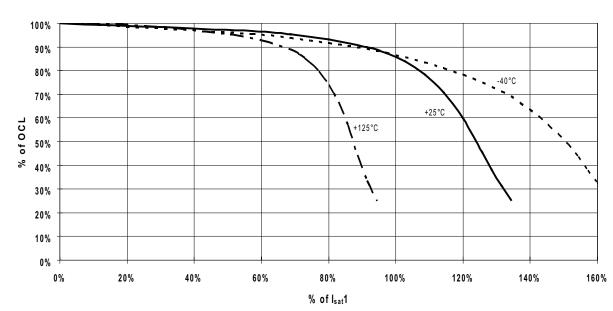


Core Loss



Inductance Characteristics

% of OCL vs. % of Isat1



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Solder Reflow Profile

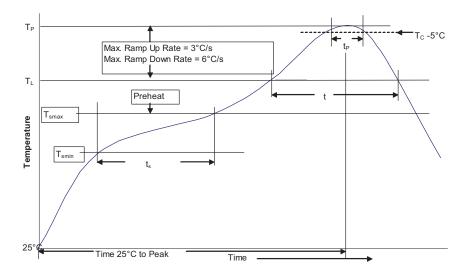


Table 1 - Standard SnPb Solder (T_c)

	Volume	Volume	
Package	mm³	mm³	
Thickness	<350	≥350	
<2.5mm	235°C	220°C	
≥2.5mm	220°C	220°C	

Table 2 - Lead (Pb) Free Solder (Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak	• Temperature min. (T _{smin})	100°C	150°C	
	Temperature max. (T _{smax})	150°C	200°C	
	• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds	
Average ramp up rate T _{smax} to T _p		3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL) Time at liquidous (t _L)		183°C 60-150 Seconds	217°C 60-150 Seconds	
Peak package body temperature (T _P)*		Table 1	Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)		20 Seconds**	30 Seconds**	
Average ramp-down rate (T _p to T _{smax})		6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.	

 $^{^{\}star}$ Tolerance for peak profile temperature ($T_{\rm p}$) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.